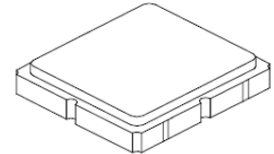


**SF2147D**

**157.0 MHz  
SAW Filter**



**SM3838-6**

- CDMA Base Station SAW Filter
- 3.8 x 3.8 x 1.4 mm Surface-mount Package
- Complies with Directive 2002/95/EC (RoHS)
- Moisture Sensitivity Level: 1

**Absolute Maximum Ratings**

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Maximum DC Voltage on any Non-ground Terminals	3	VDC
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260°C for 30 s	

**Electrical Characteristics**

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	$f_C$			157		MHz
Passband Width	BW		20			
Matched Insertion Loss, 147 to 167 MHz	IL			7.8	8.5	dB
Passband Amplitude Ripple, 147 to 167 MHz				1.2	1.8	dB <sub>P-P</sub>
Passband Group Delay, 147 to 167 MHz					0.2	µs
Passband Group Delay Ripple, 147 to 167 MHz				15	50	ns <sub>P-P</sub>
Rejection:						dB
$f_C \pm (16 \text{ to } 20 \text{ MHz})$			8	11		
$f_C \pm (20 \text{ to } 100 \text{ MHz})$			15	29		
DC to 57 MHz			35	45		
257 to 1000 MHz						
Single-ended Source Impedance			50 ohm			
Single-ended Load Impedance			50 ohm			

Case Style	SM3838-6 3.8 x 3.8 mm Nominal Footprint
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	796, <u>YWWS</u>

**Electrical Connections**

Connection	Terminals
Port 1	2
Port 2	5
Case Ground	All others

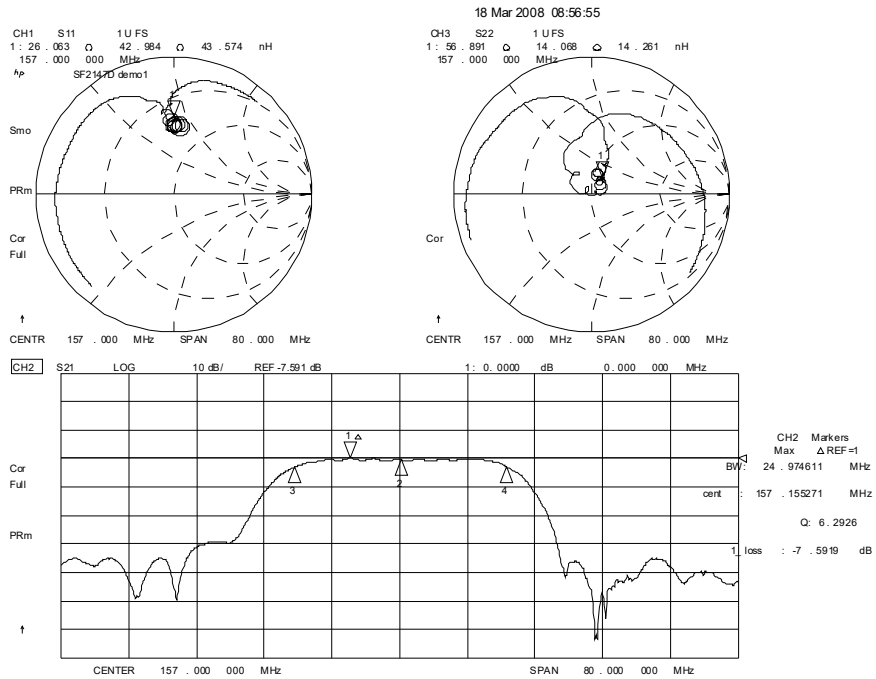


**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

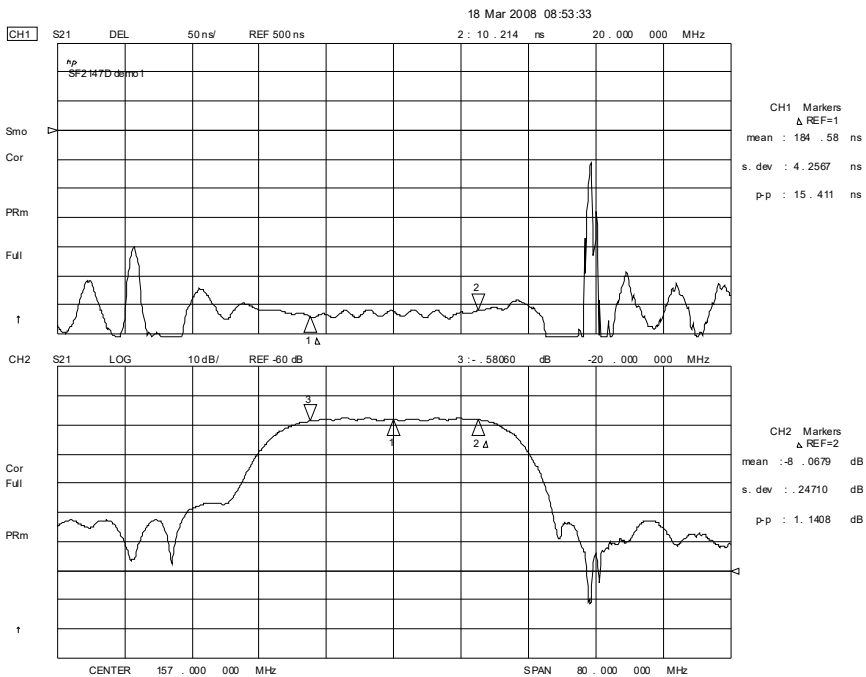
**NOTES:**

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

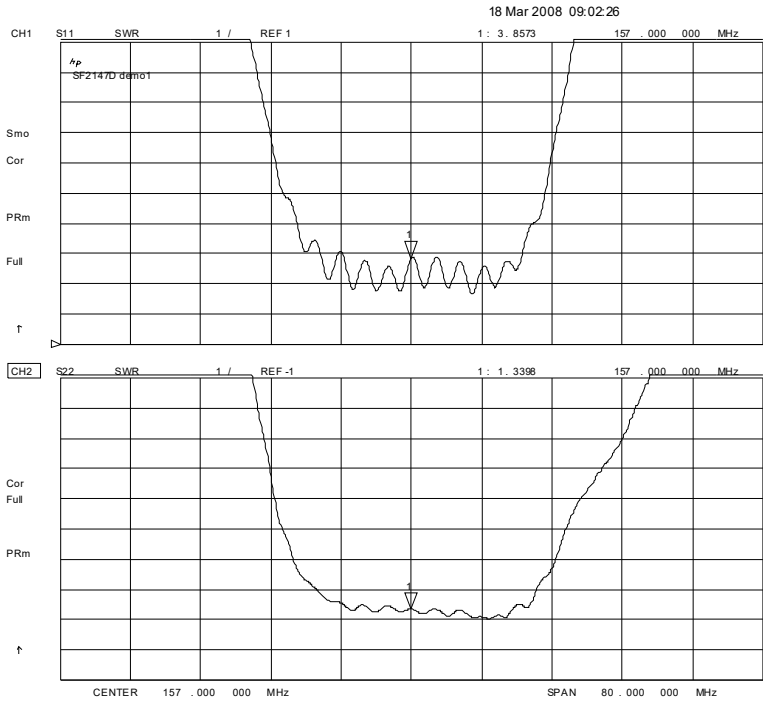
## Filter S11, S22 and S21 Plots



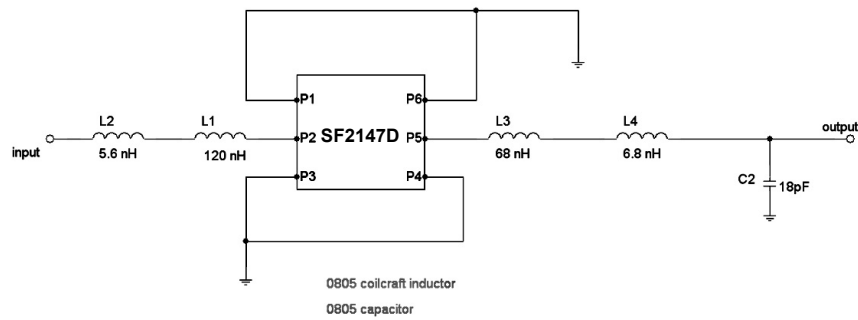
## Filter Passband Group Delay and Amplitude Plots



# Filter Input and Output VSWR Plots



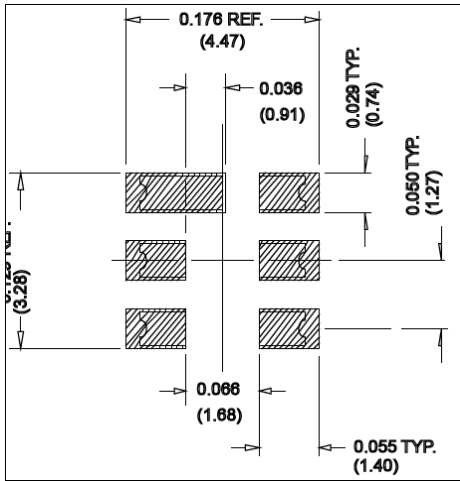
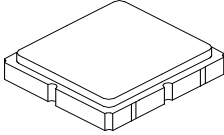
# Typical Tuning Network



# SM3838-6 Case

## 6-Terminal Ceramic Surface-Mount Case

### 3.8 X 3.8 mm Nominal Footprint



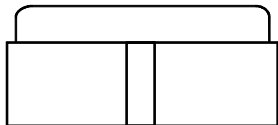
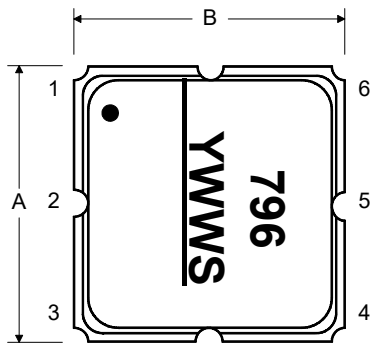
PCB Footprint

Dimension	Case Dimensions					
	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.60	3.80	4.0	0.14	0.15	0.16
B	3.60	3.80	4.0	0.14	0.15	0.16
C	1.30	1.50	1.70	0.05	0.06	0.067
D	0.95	1.10	1.25	0.037	0.043	0.05
E	2.39	2.54	2.69	0.090	0.10	0.110
G	0.90	1.0	1.10	0.035	0.04	0.043
H	1.90	2.0	2.10	0.75	0.08	0.83
I	0.50	0.6	0.70	0.020	0.024	0.028
J	1.70	1.8	1.90	0.067	0.07	0.075

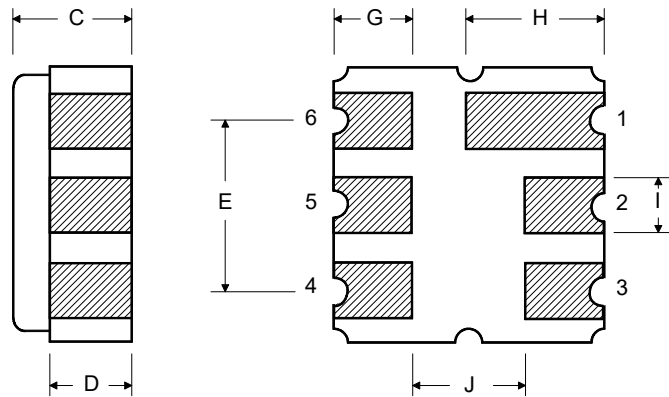
Electrical Connections		
Connection	Terminals	
Port 1	Single-ended Input	2
Port 2	Single-ended Output	5
	Ground	All others
Single-ended Operation Only		
Dot indicates Pin 1		

Materials	
Solder Pad Plating	0.3 to 1.0 $\mu\text{m}$ Gold over 1.27 to 8.89 $\mu\text{m}$ Nickel
Lid Plating	2.0 to 3.0 $\mu\text{m}$ Nickel
Body	$\text{Al}_2\text{O}_3$ Ceramic

TOP VIEW



BOTTOM VIEW





## Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

